

IEC 249:— Metal-clad base materials for printed circuits—  
249-3:1973 Special materials used in connection with printed circuits. (Superseded by a later edition).

NOTE—All parts of BS 2011 *except* Parts 2.1Kb; 2.1PZ and 2.1Z/ABDM have been replaced by IEC 68 all parts, now endorsed as suitable for use in New Zealand. See endorsed lists.

Dated at Wellington this 4th day of January 1984.

DENYS R. M. PINFOLD,  
Director, Standards Association of New Zealand.  
(S.A. 114/2/12:473-520)

NIL

*The Standards Act 1965—Overseas Specifications Endorsed as Suitable for Use in New Zealand*

PURSUANT to section 17 of the Standards Act 1965, the Standards Council, on 28 October 1983, endorsed the under-mentioned overseas specifications as suitable for use in New Zealand.

Number and Title of Specification	Price of Copy (Post free) \$	Number and Title of Specification	Price of Copy (Post free) \$
International Electrotechnical Commission		Part 2-43:1976 Test Kd:Hydrogen sulphide test for contacts and connections.	17.30
IEC 68:—Basic environmental testing procedures—		Part 2-44:1979 Guidance on test T:Soldering.	24.00
Part 1:1982 General and guidance.	60.50	Part 2-45:1980 Test XA and guidance:Immersion in cleaning solvents.	24.00
Part 2: Tests—		Part 2-46:1982 Guidance on Test Kd:Hydrogen sulphide test for contacts and connections.	30.70
Part 2-1:1974 Test A. Cold	49.90	Part 2-47:1982 Mounting of components, equipment, and other articles for dynamic tests including shock (Ea), bump (Eb), vibration (Fc and Fd) and steady-state acceleration.	32.60
Part 2-1A:1976 First supplement.	3.80	Part 2-48:1982 Guidance on the application of the tests of IEC Publication 68 to simulate the effects of storage	17.30
Part 2-2:1974 Test B:Dry heat.	66.70	Part 3:Background information—	
Part 2-2A:1976 First supplement.	3.80	Part 3-1:1974 Section 1. Cold and dry heat tests.	65.30
Part 2-3:1969 Test Ca:Damp heat, steady state.	11.10	Part 3-1A:1978 First supplement.	11.50
Part 2-5:1975 Test Sa:Simulated solar radiation at ground level.	15.40	Part 3-2:1976 Section 2. Combined temperature/low air pressure tests.	15.40
Part 2-6 1982 Test Fc and guidance:Vibration (sinusoidal)	69.10	IEC 96:— Radio-frequency tables—	
Part 2-7:1968 Test Ga: Acceleration, steady state. (Amendment No. 1:1982)	10.10 9.60	Part 3:1982 General requirements and tests for single-unit coaxial cables for use in cable distribution systems.	15.40
Part 2-9:1975 Guidance for solar radiation testing	43.70	IEC 154:—Flanges for waveguides—	
Part 2-10:1968 Test J: mould growth.	11.50	Part 3:1982 Relevant specifications for flanges for flat rectangular waveguides.	27.80
Part 2-10A:1969 First supplement. (Amendment No. 1:1972)	11.50 4.80	IEC 169:—Radio-frequency connectors—	
Part 2-11:1981 Test Ka: Salt mist.	16.30	Part 16:1982 R.F. coaxial connectors with inner diameter of outer conductor 7 mm (0.276 in) with screw coupling. Characteristic impedance 50 ohms (75 ohms) (Type N).	30.70
Part 2-13:1966 Test M: Low air pressure.	6.70	IEC 244:—Methods of measurement for radio transmitters—	
Part 2-14:1974 Test N:Change of temperature. (Amendment No. 1:1978)	28.80 9.60	Part 9:1982 Transposers for monochrome and colour television.	75.80
Part 2-17:1978 Test Q:Sealing.	69.10	IEC 304:1982 Standard colours for insulation for low-frequency cables and wires.	24.00
Part 2-20:1979 Test T:Soldering.	60.50	IEC 325:1981 Alpha, beta and alpha-beta contamination meters and monitors.	62.40
Part 2-21:1983 Test U: Robustness of terminations and integral mounting devices.	45.10	IEC 326:—Printed boards—	
Part 2-27:1972 Test Ea: Shock. (Amendment No. 1:1982)	42.20 17.30	Part 2:1976 Test methods	72.00
Part 2-28:1980 Guidance for damp heat tests.	26.90	Part 2A:1980 First supplement.	28.80
Part 2-29:1968 Test Eb: Bump. (Amendment No. 1:1982)	19.20 11.50	Part 2B:1982 Second supplement.	27.80
Part 2-30:1980 Test Db and guidance. Damp heat, cyclic. (12+12 hour cycle).	24.00	Part 3:1980 Design and use of printed boards.	59.50
Part 2-31:1969 Test Ec: Drop and topple, primarily for equipment-type specimens. (Amendment No. 1:1982)	4.80 9.60	Part 3A:1982 First supplement.	29.80
Part 2-32:1975 Test Ed:Free fall. (Amendment No. 1:1983)	15.40 9.60	Part 4:1980 Specification for single and double sided printed boards with plain holes.	26.90
Part 2-33:1971 Guidance on change of temperature tests. (Amendment No. 1:1978)	11.50 8.60	Part 5:1980 Specification for single and double sided printed boards with plated-through holes.	31.70
Part 2-34:1973 Test Fd:Random vibration wide band. General requirements.	38.40	Part 6:1980 Specification for multilayer printed boards.	38.40
Part 2-35:1973 Test Fda:Random vibration wide band. Reproducibility high.	48.00	Part 7:1981 Specification for single and double sided flexible printed boards without through connections.	33.60
Part 2-36:1973 Test Fdb:Random vibration wide band. Reproducibility medium.	48.00	Part 8:1981 Specification for single and double sided flexible printed boards with through connections.	39.40
Part 2-37:1973 Test Fdc:Random vibration wide band. Reproducibility low.	28.80	IEC 249:— Base materials for printed circuits—	
Part 2-38:1974 Test Z/AD:Composite temperature/humidity cyclic test.	24.00	Part 3: Special materials used in connection with printed circuits—	
Part 2-39:1976 Test Z/AMD:Combined sequential cold, low air pressure, and damp heat test.	13.40	Part 3-1:1981 Specification No. 1. Prepreg for use as bonding sheet material in the fabrication of multilayer printed boards.	25.90
Part 2-40:1976 Test Z/AM:Combined cold/low air pressure tests.	22.60	IEC 384:—Fixed capacitors for use in electronic equipment—	
Part 2-41:1976 Test Z/BM:Combined dry heat/low air pressure tests.	24.00	Part 15:1982 Sectional specification. Fixed tantalum capacitors with non-solid or solid electrolyte.	73.00
Part 2-42:1982 Test Kc:Sulphur dioxide test for contacts and connections.	19.20	Part 16:1982 Sectional specification. Fixed metallized polypropylene film dielectric d.c. capacitors.	65.30
		Part 16-1:1982 Blank detail specification. Fixed metallized polypropylene film dielectric d.c. capacitors. Assessment level E.	29.80
		IEC 559:1982 Binary floating point arithmetic for microprocessor systems.	46.10
		IEC 574:—Audio-visual, video and television equipment and systems—	
		Part 4:1982 Preferred matching values for the inter-connection of equipment in a system.	30.70
		Part 10:1983 Audio cassette systems.	27.80